

Features

- 25MHz crystal or CMOS input
- Generates PCIe 1, 2, 3, 4 compliant clocks
- Four default configurations selected by hardware pins at reset:
 - Config0: 100MHz on output OC1 (CML format)
 - Config1: 100MHz on OC1, OC2 (CML)
 - Config2: 100MHz on OC1 (CML), OC2 (HSTL)
 - Config3: 100MHz on OC1, OC2 (CML) and 25MHz LVCMOS on OC3
- Per-output controls (using SPI or I2C interface)
 - Per-output enable/disable and glitchless start/stop (stop high or low)
 - Precise output alignment circuitry and per-output phase adjustment

Ordering Information

ZL30281LDG1	32 Pin QFN	Trays
ZL30281LDF1	32 Pin QFN	Tape and Reel
Matte Tin		
Package size: 5 x 5 mm		
-40°C to +85°C		

General Features

- SPI or I²C processor Interface
- Tiny 5x5mm QFN package

Applications

- PCIe Gen1 to Gen4 clock generation for PCIe storage systems, riser cards, JBOF, etc.

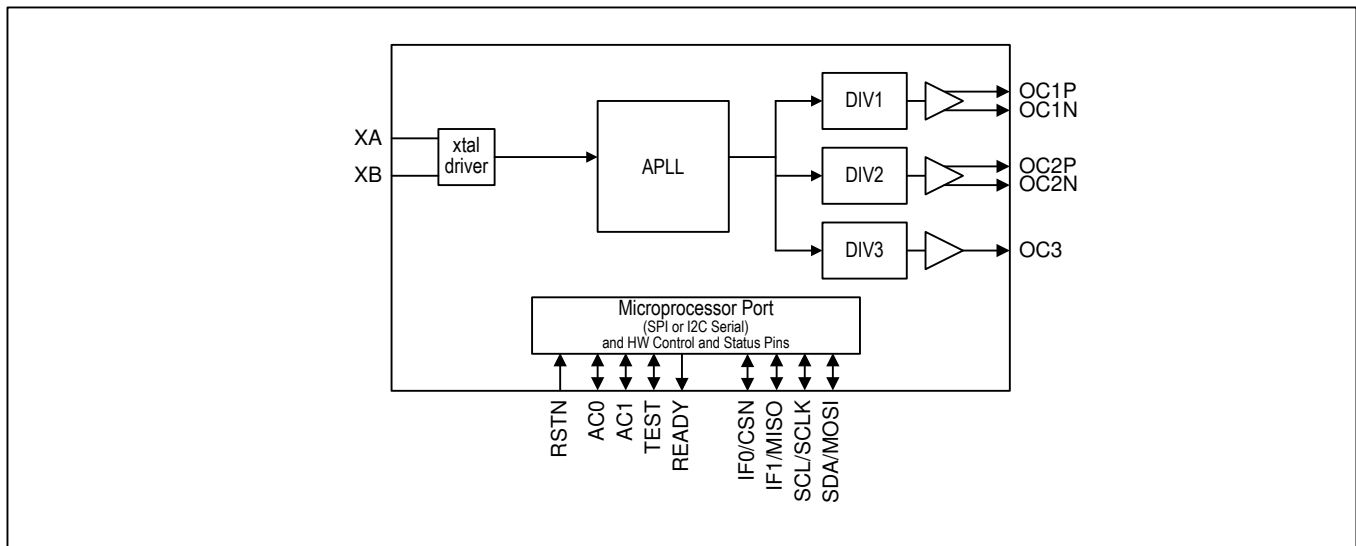


Figure 1 - Functional Block Diagram

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1. Pin Diagram

The device is packaged in a 5x5mm 32-pin QFN.

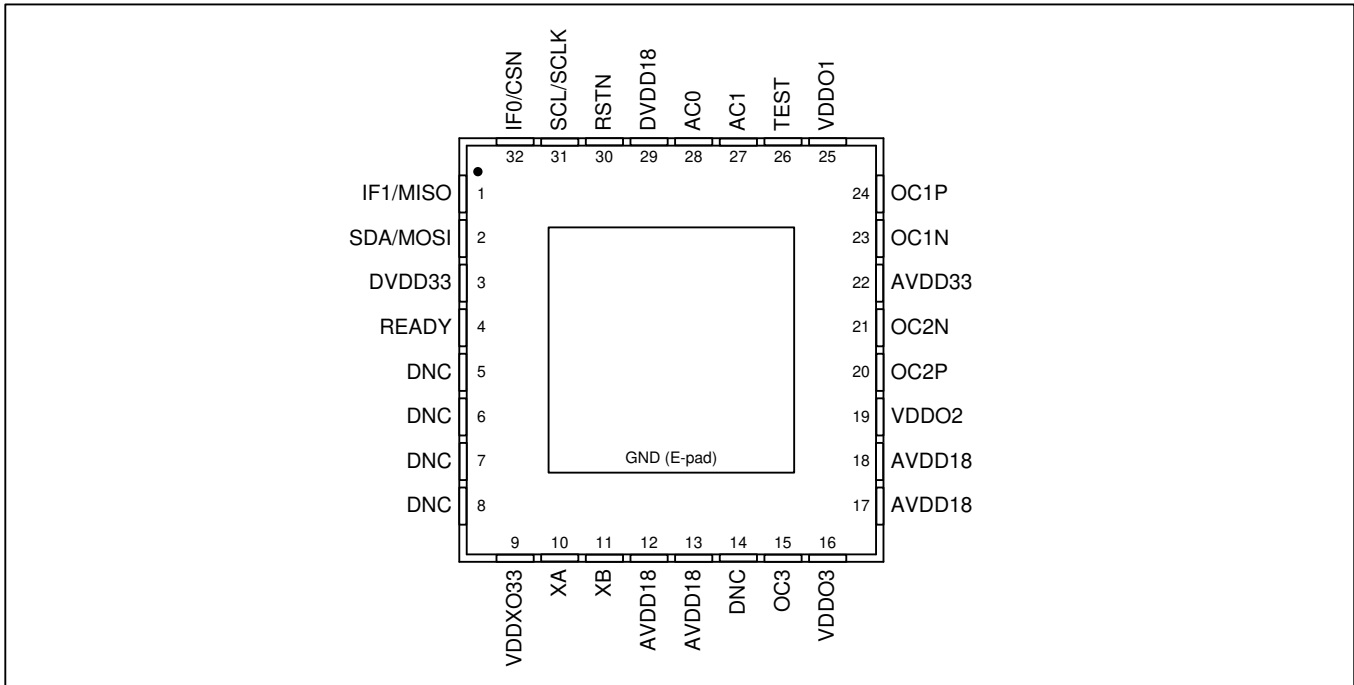


Figure 2 - Pin Diagram

2. Pin Descriptions

All device inputs and outputs are LVCMOS unless described otherwise. The Type column uses the following symbols: I – input, I_{PU} – input with 50k Ω internal pullup resistor, O – output, A – analog, P – power supply pin. All SPI/I²C interface pins have Schmitt-trigger inputs and have output drivers that can be disabled (high impedance).

Table 1 - Pin Descriptions

Pin #	Name	Type	Description
10 11	XA XB	A / I	<p>Crystal or Input Clock Pins <i>Crystal:</i> MCR1.XAB=01. An on-chip crystal driver circuit is designed to work with an external crystal connected to the XA and XB pins. See section 3.2.2 for crystal characteristics and recommended external components.</p> <p><i>Input Clock:</i> MCR1.XAB=10. An external local oscillator or clock signal can be connected to the XA pin. The XB pin must be left unconnected.</p>
24 23 20 21 15	OC1P OC1N OC2P OC2N OC3	O	<p>Output Clock Pins CML, HSTL or CMOS. Programmable frequency and drive strength. See Table 9 and Figure 9 for electrical specifications and recommended external circuitry for interfacing to LVDS, LVPECL or CML input pins on neighboring devices. See Table 10 for electrical specifications for interfacing to CMOS and HSTL inputs on neighboring devices. See Figure 10 for recommended external circuitry for interfacing to HCSL inputs on neighboring devices.</p>

Pin #	Name	Type	Description
30	RSTN	I _{PU}	Reset (Active Low) When this global asynchronous reset is pulled low, all internal circuitry is reset to default values. The device is held in reset as long as RSTN is low. See section 3.5.
28 27	AC0 AC1	I	Auto-Configure [1:0] On the rising edge of RSTN these pins specify the device configuration. See section 3.1.
26	TEST	I	Factory Test On the rising edge of RSTN the pin behaves as TEST. Factory test mode is enabled when TEST is high. For normal operation TEST must be low on the rising edge of RSTN.
4	READY	O	PLL Lock This pin indicates the state of the device after reset. 0=not ready, 1=ready.
32	IF0/CSN	I/O	Interface Mode 0 / SPI Chip Select (Active Low) <i>Interface Mode:</i> On the rising edge of RSTN the pin behaves as IF0 and, together with IF1, specifies the interface mode for the device. See section 3.1. <i>SPI Chip Select:</i> After reset this pin is CSN. An external SPI master must assert (low) CSN to access device registers.
31	SCL/SCLK	I/O	I²C Clock / SPI Clock <i>I²C Clock:</i> When the device is configured as an I ² C slave, an external I ² C master must provide the I ² C clock signal on the SCL pin. <i>SPI Clock:</i> An external SPI master must provide the SPI clock signal on SCLK.
1	IF1/MISO	I/O	Interface Mode 1 / SPI Master-In-Slave-Out <i>Interface Mode:</i> On the rising edge of RSTN the pin behaves as IF1 and, together with IF0, specifies the interface mode for the device. See section 3.1. <i>SPI MISO:</i> After reset this pin is MISO. The device outputs data to an external SPI master on MISO during SPI read transactions
2	SDA/MOSI	I/O	I²C Data / SPI Master-Out-Slave-In <i>I²C Data:</i> When the device is configured as an I ² C slave, SDA is the bidirectional data line between the device and an external I ² C master. <i>SPI MOSI:</i> An external SPI master sends commands, addresses and data to the device on MOSI.
12 13 17 18	AVDD18	P	Analog Power Supply. 1.8V ±5%.
22	AVDD33	P	Analog Power Supply. 3.3V ±5%.
29	DVDD18	P	Digital Power Supply. 1.8V ±5%.
3	DVDD33	P	Digital Power Supply. 3.3V ±5%.
25	VDDO1	P	Output OC1 Power Supply. 1.5V to 3.3V ±5%.
19	VDDO2	P	Output OC2 Power Supply. 1.5V to 3.3V ±5%.
16	VDDO3	P	Output OC3 Power Supply. 1.5V to 3.3V ±5%.
9	VDDXO33	P	Analog Power Supply for Crystal Driver Circuitry. 3.3V ±5%.
5, 6, 7, 8, 14	DNC		Do Not Connect. Leave these pins floating.

Pin #	Name	Type	Description
E-pad	VSS	P	Ground. 0 Volts.

3. Functional Description

3.1 Pin-Controlled Automatic Configuration at Reset

The device configuration is determined at reset (i.e. on the rising edge of RSTN) by the signal levels on five device pins: TEST, AC1, AC0, IF1/MISO and IF0/CSN. For each of these pins, the first name (TEST, AC1, AC0, IF1, IF0) indicates their function when they are sampled by the rising edge of the RSTN pin. The second name refers to their function after reset. The values of these pins are latched into the [CFGSR](#) register when RSTN goes high. To ensure the device properly samples the reset values of these pins, the following guidelines should be followed:

1. Any pullup or pulldown resistors used to set the value of these pins at reset should be 1kΩ.
2. RSTN must be asserted at least as long as specified in section [3.5](#).

The hardware configuration pins are grouped into three sets:

1. TEST - Manufacturing test mode
2. IF[1:0] – Microprocessor interface mode and I²C address
3. AC[1:0] – Auto-configuration

The TEST pin selects manufacturing test modes when TEST=1. Therefore TEST should be pulled low.

The IF[1:0] pins specify the processor interface mode and the I²C slave address. The AC[1:0] pins specify which of four device configurations to execute after reset.

IF1	IF0	Processor Interface
0	0	I ² C, slave address 11011 00
0	1	I ² C, slave address 11011 01
1	0	I ² C, slave address 11011 10
1	1	SPI Slave

AC1	AC0	Auto Configuration
0	0	Config0: 100MHz on OC1 (CML signal format)
0	1	Config1: 100MHz on OC1 and OC2 (CML)
1	0	Config2: 100MHz on OC1 (CML) and OC2 (HSTL format)
1	1	Config3: 100MHz on OC1 and OC2 (CML) and 25MHz LVCMOS on OC3

All four configurations set up the part to use a 25MHz crystal on XA and XB as the input reference.

3.2 Local Oscillator or Crystal

Section [3.2.1](#) describes how to connect an external oscillator and the required characteristics of the oscillator. Section [3.2.2](#) describes how to connect an external crystal to the on-chip crystal driver circuit and the required characteristics of the crystal.

3.2.1 External Oscillator

A 25MHz signal from an external oscillator can be connected to the XA pin (XB must be left unconnected). To minimize jitter, the signal must be properly terminated and must have very short trace length. A poorly terminated single-ended signal can greatly increase output jitter, and long single-ended trace lengths are more susceptible to noise. When [MCR1.XAB=10](#), XA is enabled as a single-ended input.

The jitter on output clock signals depends on the phase noise and frequency of the external oscillator.

3.2.2 External Crystal and On-Chip Driver Circuit

The on-chip crystal driver circuit is designed to work with a 25MHz fundamental mode, AT-cut crystal resonator. See [Table 2](#) for recommended crystal specifications. To enable the crystal driver, set [MCR1.XAB=01](#).

See Figure 3 for the crystal equivalent circuit and the recommended external capacitor connections. To achieve a crystal load (C_L) of 10pF, an external 16pF (C_1) is placed in parallel with the 4pF internal capacitance of the XA pin, and an external 16pF (C_2) is placed in parallel with the 4pF internal capacitance of the XB pin. The crystal then sees a load of 20pF in series with 20pF, which is 10pF total load. Note that the 16pF capacitance include all capacitance on those nodes. If, for example, PCB trace capacitance between crystal pin and IC pin is 2pF then 14pF capacitors should be used to make 16pF total.

The crystal, traces, and two external capacitors should be placed on the board as close as possible to the XA and XB pins to reduce crosstalk of active signals into the oscillator. Also no active signals should be routed under the crystal circuitry.

Note: Crystals have temperature sensitivities that can cause frequency changes in response to ambient temperature changes. In applications where significant temperature changes are expected near the crystal, it is recommended that the crystal be covered with a thermal cap, or an external XO should be used instead.

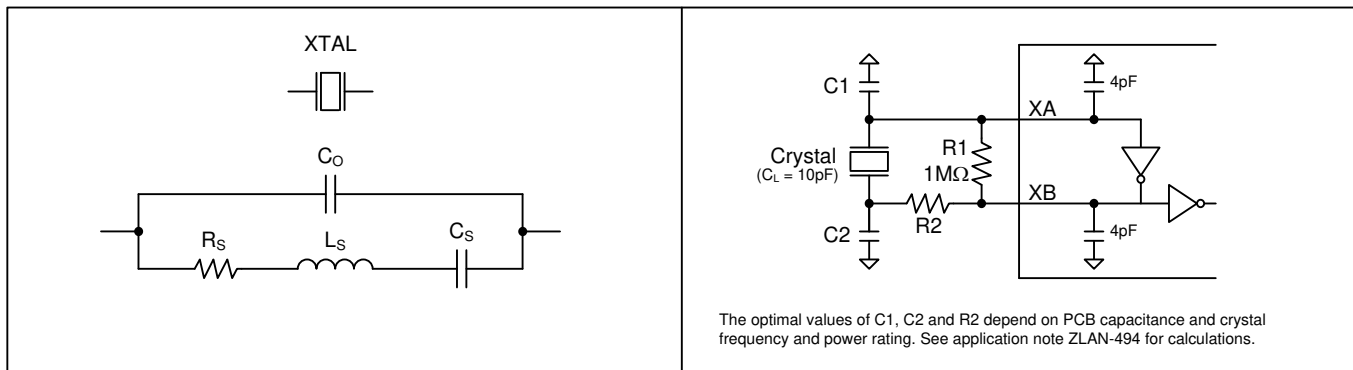


Figure 3 - Crystal Equivalent Circuit / Recommended Crystal Circuit

Table 2 - Crystal Selection Parameters

Parameter	Symbol	Min.	Typ.	Max.	Units
Crystal oscillation frequency ¹	f_{osc}		25		MHz
Shunt capacitance	C_0		2	5	pF
Load capacitance	C_L		10		pF
Equivalent series resistance (ESR) ²	$f_{osc} < 40\text{MHz}$	R_s		60	Ω
	$f_{osc} > 40\text{MHz}$	R_s		50	Ω
Maximum crystal drive level		100			μW

Note 1: Higher frequencies give lower output jitter, all else being equal.

Note 2: These ESR limits are chosen to constrain crystal drive level to less than 100 μW . If the crystal can tolerate a drive level greater than 100 μW then proportionally higher ESR is acceptable.

Parameter	Symbol	Min.	Typ.	Max.	Units
Crystal Frequency Stability vs. Power Supply	f_{VD}		0.2	0.5	ppm per 10% Δ in VDD

3.3 Output Clock Configuration

The device has three output clock signal pairs. Each output has individual enable, start/stop and alignment controls. The outputs can be aligned relative to each other, and the phases of output signals can be adjusted dynamically with high resolution and infinite range.

3.3.1 Output Signal Format, Voltage and Interfacing

The signal format of each output is determined by the configuration number specified by the AC[1:0] pins at device reset (see the AC[1:0] table in section 3.1). The clock to the output driver can be inverted by setting $OCxCR2.POL=1$. The CMOS/HSTL output driver can be set to any of four drive strengths using $OCxCR2.DRIVE$.

Each output has its own power supply pin to allow CMOS or HSTL signal swing from 1.5V to 3.3V for glueless interfacing to neighboring components. If OC2 is HSTL format (Config2) then a 1.8V VDDO2 voltage can be used to as shown in [Figure 10](#) to get a signal compatible with HCSL receivers. Note that CML outputs must have a power supply voltage of 3.3V.

The CML outputs can be easily interfaced to LVDS, LVPECL, CML, HCSL, HSTL and other differential inputs on neighboring ICs using a few external passive components. See [Figure 9](#) for examples.

3.3.2 Output Phase Adjustment and Phase Alignment

The device has flexible, high-resolution tools for managing the phases of the output clocks relative to one another. The key register fields for this are found in the [PACR1](#) global configuration register and the per-output [OCxPH](#) register. Resolution is one period of the 600MHz APLL clock, i.e. 1.667ns.

3.3.2.1 Phase Adjustment

A phase adjustment is a phase change for an output relative to that output's most recent phase. To cause the device to perform phase adjustment of an output clock, set [PACR1.MODE=1](#), set [OCxCR1.PHEN=1](#) to enable the output for phase adjustment, and write the phase adjustment amount to the output's [OCxPH](#) register. Then an arm/trigger methodology is used to cause the phase adjustment to happen.

The arm step tells the device that it is enabled to perform the phase adjustment when it sees the trigger stimulus. The arm signal is a 0-to-1 transition of the [PACR1.ARM](#) bit. The trigger signal a 0-to-1 transition of the [PACR1.TRIG](#) bit. Any combination of outputs can be phase adjusted by the same trigger, and each output can be adjusted by a different amount. Only outputs with [OCxCR1.PHEN=1](#) and [OCxPH.PHADJ≠0](#) have their phases adjusted.

There are a few constraints on the range of possible phase adjustments. The largest negative phase adjustment is 2 APLL periods, which is $2 * 1.667ns = 3.333ns$. The largest positive phase adjustment is 6 APLL periods, which is $6 * 1.667ns = 10ns$.

An armed phase adjustment can be canceled before the trigger occurs by setting the [PACR1.RST](#) bit.

The [PASR](#) register has real-time status bits indicating whether a phase adjustment is armed and waiting for a trigger (ARMED bit) or in progress (BUSY bit). It also has a latched status bit (ADJL bit) to indicate the adjustment has completed.

Example: +1.0 APLL period phase adjustment for output OC1:

```

OC1CR1.PHEN=1      (Enable phase adjust on OC1)
OC1PH.PHADJ=0000010 (Specify +1.0 APLL period phase adjustment, i.e. 1.667ns)
PACR1.MODE=1      (Phase adjustment mode)
PACR1.RST=1       (reset phase adjust/align state machine)
PACR1.ARM=1       (arm for phase adjust)
PACR1.TRIG=1      (trigger the phase adjust: add +1.0 UI to output phase)
repeat the next two writes as needed:
PACR1.ARM=1 .TRIG=0 (arm again; clearing the TRIG bit is required)
PACR1.TRIG=1      (trigger again: add +1.0 APLL period to output phase again)

```

3.3.2.2 Phase Alignment, Output-to-Output

A phase alignment is a special case of phase adjustment where the dividers for all participating outputs are reset just before the phase adjustment occurs.

To avoid glitches (i.e. "runt pulses") on the output clock it is possible to manually stop the output(s), before triggering the phase alignment, and then restart the output(s) after the alignment (See section [3.3.3](#)).

When aligning outputs, it is important to note that, by default, the phase of outputs configured as HSTL format is opposite that of CML outputs. For example, consider the case where OC1 is 100MHz CML format and OC2 is 100MHz HSTL format. When OC1 and OC2 are aligned then OC2N is high when OC1P is high. The polarity bit `OCxCR2.POL` can be used to change this as needed.

Contact Microsemi Timing Applications Support for help with alignment scenarios that don't meet the rules listed above.

Example: OC1-to-OC2 alignment (+3.5 APLL cycle offset):

```

OC1CR1.PHEN=1      (Enable phase adjust on OC1)
OC2CR1.PHEN=1      (Enable phase adjust on OC2)
OC1PH.PHADJ=00000000 (0.0UI)
OC2PH.PHADJ=00000111 (+3.5UI)
PACR1.MODE=0       (Phase alignment mode)
PACR1.RST=1        (reset phase adjust/align state machine)
PACR1.ARM=1        (arm for phase alignment)
PACR1.TRIG=1       (trigger the phase alignment)

```

3.3.3 Output Clock Start, Stop and High-Impedance

Output clocks can be stopped high or low. One use for this behavior is to ensure “glitchless” output clock operation while the output is reconfigured or phase aligned with some other signal.

Each output has an `OCxSTOP` register with fields to control this behavior. The `OCxSTOP.MODE` field specifies whether the output clock signal stops high, stops low, or does not stop. The `OCxSTOP.SRC` field specifies the source of the stop signal. Options include the `OCxSTOP.STOP` bit and the arming of a phase adjustment (which is indicated by `PASR.ARMED`).

When the stop mode is Stop High (`OCxSTOP.MODE=01`) and the stop signal is asserted, the output clock is stopped after the next rising edge of the output clock. When the stop mode is Stop Low (`OCxSTOP.MODE=10`) and the stop signal is asserted, the output clock is stopped after the next falling edge of the output clock. Internally the clock signal continues to toggle while the output is stopped. When the stop signal is deasserted, the output clock resumes on the opposite edge that it stopped on.

When `OCxCR2.POL=1` the output stops on the opposite polarity that is specified by the `OCxSTOP.MODE` field.

When `OCxCR2.STOPDIS=1` the output driver is disabled (high impedance) while the output clock is stopped.

Each output has a status register (`OCxSR`) with several stop/start status bits. The `STOPD` bit is a real-time status bit indicating stopped or not stopped. The `STOPL` bit is a latched status bit that is set when the output clock has stopped. The `STARTL` bit is a latched status bit that is set when the output clock has started.

3.4 Microprocessor Interface

The device can communicate over a SPI interface or an I²C interface.

In SPI mode the device can only be configured as a SPI slave to a processor master. The device is always a slave on the I²C bus.

Section 3.1 describes reset pin settings required to configure the device for these interfaces.

3.4.1 SPI Slave

The device can present a SPI slave port on the CSN, SCLK, MOSI, and MISO pins. SPI is a widely used master/slave bus protocol that allows a master and one or more slaves to communicate over a serial bus. SPI masters are typically microprocessors, ASICs or FPGAs. Data transfers are always initiated by the master, which also generates the SCLK signal. The device receives serial data on the MOSI (Master Out Slave In) pin and

transmits serial data on the MISO (Master In Slave Out) pin. MISO is high impedance except when the device is transmitting data to the bus master.

Bit Order. The register address and all data bytes are transmitted most significant bit first on both MOSI and MISO.

Clock Polarity and Phase. The device latches data on MOSI on the rising edge of SCLK and updates data on MISO on the falling edge of SCLK. SCLK does not have to toggle between accesses, i.e., when CSN is high.

Device Selection. Each SPI device has its own chip-select line. To select the device, the bus master drives its CSN pin low.

Command and Address. After driving CSN low, the bus master transmits an 8-bit command followed by a 16-bit register address. The available commands are shown below.

Table 3 - SPI Commands

Command	Hex	Bit Order, Left to Right
Write	0x02	0000 0010
Read	0x03	0000 0011

Read Transactions. After driving CSN low, the bus master transmits the read command followed by the 16-bit address. The device then responds with the requested data byte on MISO, increments its address counter, and prefetches the next data byte. If the bus master continues to demand data, the device continues to provide the data on MISO, increment its address counter, and prefetch the following byte. The read transaction is completed when the bus master drives CSN high. See [Figure 4](#).

Write Transactions. After driving CSN low, the bus master transmits the write command followed by the 16-bit register address followed by the first data byte to be written. The device receives the first data byte on MOSI, writes it to the specified register, increments its internal address register, and prepares to receive the next data byte. If the master continues to transmit, the device continues to write the data received and increment its address counter. The write transaction is completed when the bus master drives CSN high. See [Figure 5](#).

Early Termination of Bus Transactions. The bus master can terminate SPI bus transactions at any time by pulling CSN high. In response to early terminations, the device resets its SPI interface logic and waits for the start of the next transaction. If a write transaction is terminated prior to the SCLK edge that latches the least significant bit of a data byte, the data byte is not written.

Design Option: Wiring MOSI and MISO Together. Because communication between the bus master and the device is half-duplex, the MOSI and MISO pins can be wired together externally to reduce wire count. To support this option, the bus master must not drive the MOSI/MISO line when the device is transmitting.

AC Timing. See [Table 13](#) and [Figure 11](#) for AC timing specifications for the SPI interface.

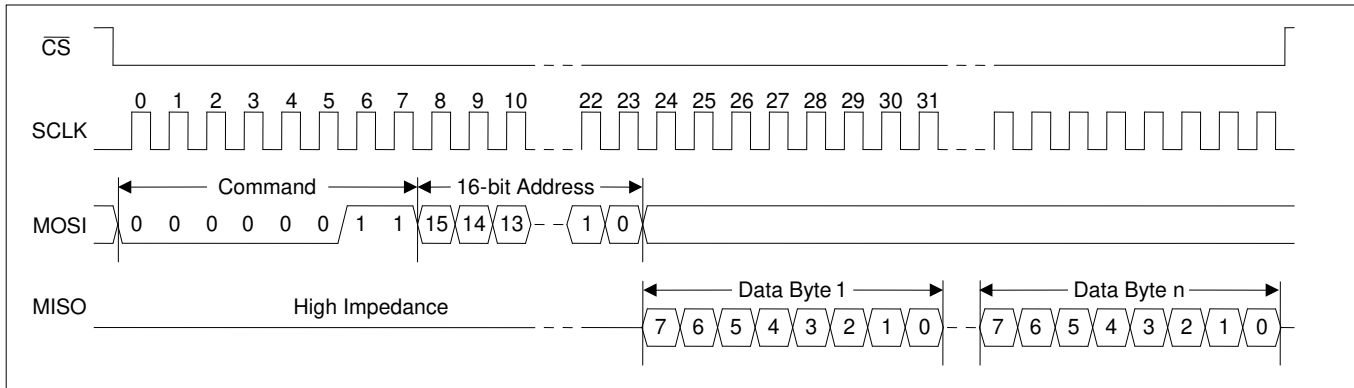


Figure 4 - SPI Read Transaction Functional Timing

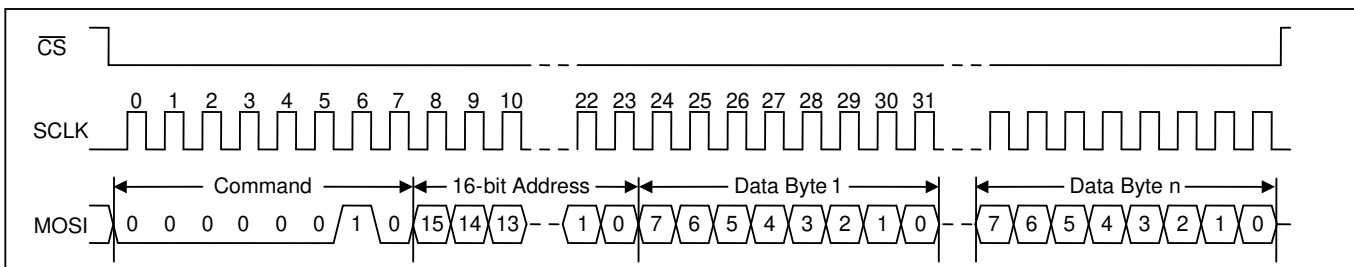


Figure 5 - SPI Write Transaction Functional Timing

3.4.2 I²C Slave

The device can present a fast-mode (400kbit/s) I²C slave port on the SCL and SDA pins. I²C is a widely used master/slave bus protocol that allows one or more masters and one or more slaves to communicate over a two-wire serial bus. I²C masters are typically microprocessors, ASICs or FPGAs. Data transfers are always initiated by the master, which also generates the SCL signal. The device is compliant with version 2.1 of the I²C specification.

The I²C interface on the device is a protocol translator from external I²C transactions to internal SPI transactions. This explains the slightly increased protocol complexity described in the paragraphs that follow.

Read Transactions. The bus master first does an I²C write to the device. In this transaction three bytes are written: the SPI Read command (see Table 3), the upper byte of the register address, and the lower byte of the register address. The bus master then does an I²C read. During each acknowledge (A) bit the device fetches data from the read address and then increments the read address. The device then transmits the data to the bus master during the next 8 SCL cycles. The bus master terminates the read with a not-acknowledge (NA) followed by a STOP condition (P). See Figure 6. Note: If the I²C write is separated in time from the I²C read by other I²C transactions then the device only outputs the data value from the first address and repeats that same data value after each acknowledge (A) generated by the bus master.

Write Transactions. The bus master does an I²C write to the device. The first three bytes of this transaction are the SPI Write command (see Table 3), the upper byte of the register address, and the lower byte of the register address. Subsequent bytes are data bytes to be written. After each data byte is received, the device writes the byte to the write address and then increments the write address. The bus master terminates the write with a STOP condition (P). See Figure 7.

I²C Features Not Supported by the Device. The I²C specification has several optional features that are not supported by the device. These are: 3.4Mbit/s high-speed mode (Hs-mode), 10-bit device addressing, general call address, software reset, and device ID. The device does not hold SCL low to force the master to wait.

I²C Slave Address. The device’s 7-bit slave address can be pin-configured for any of three values. These values are show in the table in section 3.1.

Bit Order. The I²C specification requires device address, register address and all data bytes to be transmitted most significant bit first on the SDA signal.

Note: as required by the I²C specification, when power is removed from the device, the SDA and SCL pins are left floating so they don’t obstruct the bus lines.

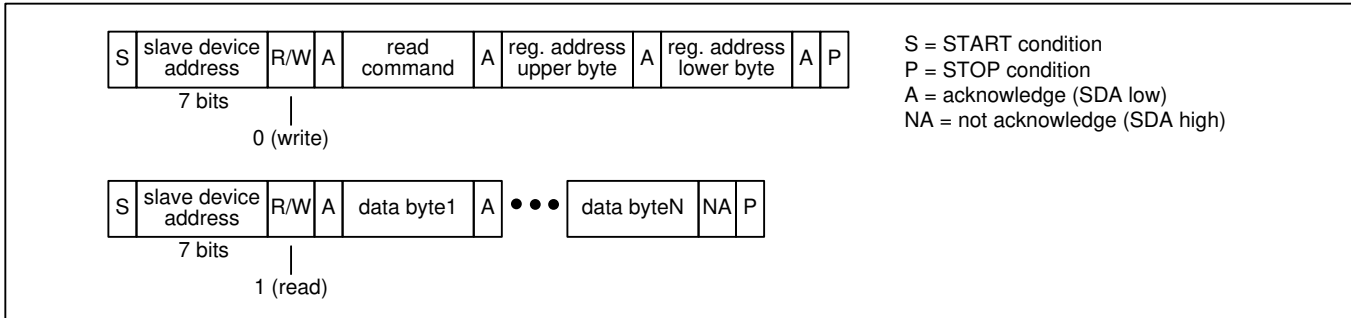


Figure 6 - I²C Read Transaction Functional Timing

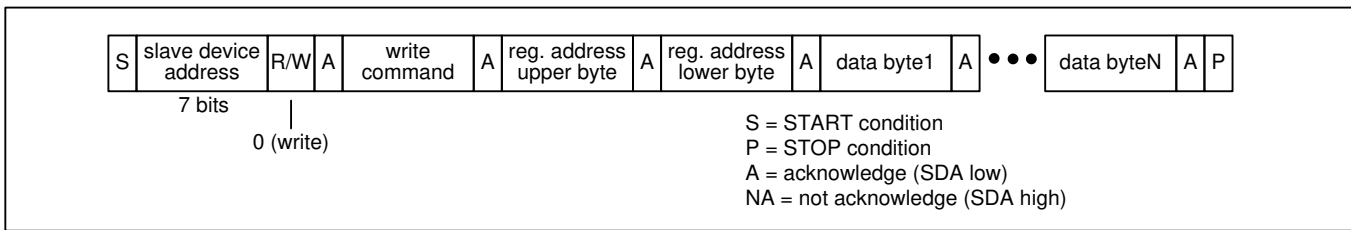


Figure 7 - I²C Write Transaction Functional Timing

Note: In Figure 6 and Figure 7, a STOP condition (P) immediately followed by a START condition (S) can be replaced by a repeated START condition (Sr) as described in the I²C specification.

3.5 Reset Logic

The device has two reset controls: the RSTN pin and the RST bit in [MCR1](#). The RSTN pin asynchronously resets the entire device. When the RSTN pin is low all internal registers are reset to their default values. **The RSTN pin must have one rising edge after power-up.** At initial power-up reset should be asserted for at least 1 μ s. During operation, the RSTN assertion time can be as short as 1 μ s with one important exception:

Consider the IF1/MISO pin: If (1) the pin could be an output driving high when RSTN is asserted, and (2) an external pulldown resistor is used to set the at-reset value of the pin, then RSTN should be asserted for 100 milliseconds.

The [MCR1](#).RST bit resets the entire device (except for the microprocessor interface and the RST bit itself), but when the RST bit is active, the register fields with pin-programmed defaults do not latch their values from, or based on, the corresponding input pins. Instead these fields are reset to the default values that were latched when the RSTN pin was last active.

Important: System software must wait at least 100 μ s after RSTN is deasserted and wait for [GLOBISR.READY=1](#) before configuring the device.

3.6 Power-Supply Considerations

Due to the multi-power-supply nature of the device, some I/Os have parasitic diodes between a <3.3V supply and a 3.3V supply. When ramping power supplies up or down, care must be taken to avoid forward-biasing these diodes because it could cause latchup. Two methods are available to prevent this. The first method is to place a Schottky diode external to the device between the <3.3V supply and the 3.3V supply to force the 3.3V supply to be within one parasitic diode drop of the <3.3V supply. The second method is to ramp up the 3.3V supply first and then ramp up the <3.3V supply. In some applications VDDOx power supply pins can be at other voltages, such as 2.5V or 1.5V. In these applications the general solution is to ramp up the supplies in order from highest nominal to lowest nominal voltage.

4. Register Descriptions

The device has an overall address range from 000h to 1FFh. [Table 4](#) shows the register map. In each register, bit 7 is the MSb and bit 0 is the LSb. Register addresses not listed and bits marked “—” are reserved and must be written with 0. Writing other values to these registers may put the device in a factory test mode resulting in undefined operation. Bits labeled “0” or “1” must be written with that value for proper operation. Register fields with underlined names are read-only fields; writes to these fields have no effect. All other fields are read-write. Register fields are described in detail in the register descriptions that follow [Table 4](#).

4.1 Register Types

4.1.1 Status Bits

The device has two types of status bits. Real-time status bits are read-only and indicate the state of a signal at the time it is read. Latched status bits are set when a signal changes state (low-to-high, high-to-low, or both, depending on the bit) and cleared when written with a logic 1 value. Writing a 0 has no effect. Status bits marked “—” are reserved and must be ignored.

4.1.2 Configuration Fields

Configuration fields are read-write. During reset, each configuration field reverts to the default value shown in the register definition. Configuration register bits marked “—” are reserved and must be written with 0.

4.2 Register Map

Table 4 - Register Map

ADDR	REGISTER	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	
Global Configuration Registers										
09	MCR1	RST	—	—	—	—	—	XAB[1:0]		
1B	PACR1	RST	TRIG	ARM	—	—	—	—	MODE	
Status Registers										
30	ID1	IDU[7:0]								
31	ID2	IDL[3:0]				REV[3:0]				
40	CFGSR	TEST	XOFAIL	—	—	IF[1:0]		AC[1:0]		
43	GLOBISR	READY	—	—	—	—	—	—	—	
48	APLLSR	—	—	ALK2L	ALK2	—	—	ALKL	ALK	
4D	PASR	—	—	—	—	—	ADJL	BUSY	ARMED	
53	OC1SR	—	—	—	—	STARTL	—	STOPL	STOPD	
54	OC2SR	—	—	—	—	STARTL	—	STOPL	STOPD	
55	OC3SR	—	—	—	—	STARTL	—	STOPL	STOPD	
Output Clock Configuration Registers										
OC1 Registers										
200	OC1CR1	PHEN	—	—	—	—	—	—	—	
201	OC1CR2	—	POL	DRIVE[1:0]		STOPDIS	—	—	—	
207	OC1PH	PHADJ[7:0]								
208	OC1STOP	STOP	—	SRC[3:0]				MODE[1:0]		
OC2 Registers										
210	OC2CR1	PHEN	—	—	—	—	—	—	—	
211	OC2CR2	—	POL	DRIVE[1:0]		STOPDIS	—	—	—	
217	OC2PH	PHADJ[7:0]								
218	OC2STOP	STOP	—	SRC[3:0]				MODE[1:0]		
OC3 Registers										
220	OC3CR1	PHEN	—	—	—	—	—	—	—	
221	OC3CR2	—	POL	DRIVE[1:0]		STOPDIS	—	—	—	
227	OC3PH	PHADJ[7:0]								
228	OC3STOP	STOP	—	SRC[3:0]				MODE[1:0]		

4.3 Register Definitions

4.3.1 Global Configuration Registers

Register Name: MCR1
Register Description: Master Configuration Register 1
Register Address: 09h

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Name	RST	—	—	—	—	—	XAB[1:0]	
Default	0	0	0	0	0	0	0	1

Bit 7: Device Reset (RST). When this bit is high the entire device is held in reset, and all register fields, except the RST bit itself, are reset to their default states. When RST is high, the register fields with pin-programmed defaults do not latch their values from the corresponding input pins. Instead these fields are reset to the default values that were latched from the pins when the RSTN pin was last active. See section 3.5.

0 = Normal operation

1 = Reset

Note: For proper sequencing of internal logic, write MCR1 to clear the MCSEL1, MCSEL and ROSCD bits first (without changing the value of the RST bit) then perform a second write to set the RST bit.

(Note: on rev A devices (ID2.REV=0) do not set this bit to 1.)

Bits 1 to 0: XA/XB Pin Mode (XAB[1:0]). This field specifies the behavior of the XA and XB pins. See section 3.2.

00 = Crystal driver and input disabled / powered down

01 = Crystal driver and input enabled on XA/XB

10 = XA enabled as single-ended input for external oscillator signal; XB must be left floating

11 = {unused value}

Register Name: PACR1
Register Description: Phase Adjust Configuration Register 1
Register Address: 1Bh

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Name	RST	TRIG	ARM	—	—	—	—	MODE
Default	0	0	0	0	0	0	0	0

Bit 7: Phase Adjustment Reset Bit (RST). This bit is used to reset the phase adjustment state machine. This is used to abort the phase adjustment after arming but before the trigger occurs. Resetting puts the state machine back to waiting for an arm signal. This bit is self-clearing. See section 3.3.2.

1 = Reset a phase adjustment event in progress, self clearing

Bit 6: Phase Adjustment Trigger Bit (TRIG). This bit is used to trigger the phase adjustment event after the phase adjustment has been armed. This bit is self-clearing and must be written again to cause another trigger. The ARM bit must be set first then the TRIG bit can be set in a subsequent register write to initiate a trigger event. See section 3.3.2.

1 = Trigger a phase adjustment, self clearing

Bit 5: Phase Adjustment Arm Bit (ARM). Setting this bit to 1 while PASR.ARMED=0 arms the phase adjustment. Writing a 0 to this bit has no effect. Changing the value of this bit from 0 to 1 while PASR.ARMED=1 has no effect. See section 3.3.2.

1 = Arm the phase adjustment, self clearing

Bit 0: Phase Adjust/Alignment Mode (MODE). This field sets the mode of the phase change. In output phase alignment mode, the device aligns all participating outputs and then adjusts the phase of each participating output

as specified in the **OCxPH** register. In output phase *adjustment* mode the device does align the outputs and therefore causes each participating output to have the phase adjustment specified in the **OCxPH** register relative to that output's previous phase. See section 3.3.2.

- 0 = Phase alignment mode
- 1 = Phase adjustment mode

4.3.2 Status Registers

Register Name: ID1
Register Description: Device Identification Register, MSB
Register Address: 30h

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Name	IDU[7:0]							
Default	0	0	0	1	1	0	0	1

Bits 7 to 0: Device ID Upper (IDU[7:0]). This field is the upper eight bits of the device ID.

Register Name: ID2
Register Description: Device Identification Register, LSB and Revision
Register Address: 31h

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Name	IDL[3:0]				REV[3:0]			
Default	0	0	0	1	0	0	0	1

Bits 7 to 4: Device ID Lower (IDL[3:0]). This field is the lower four bits of the device ID.

Bits 3 to 0: Device Revision (REV[3:0]). These bits are the device hardware revision starting at 0.

Register Name: CFGSR
Register Description: Configuration Status Register
Register Address: 40h

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Name	TEST	XOFAIL	—	—	IF[1:0]		AC[1:0]	
Default	see below	0	0	0	see below	see below	see below	see below

Bit 7: Test Mode (TEST). This read-only bit is the latched state of the TEST pin when the RSTN pin transitions high. For proper operation it should be 0. See section 3.1.

Bit 6: XO Fail (XOFAIL). This read-only bit is set when the external oscillator signal on the XA pin fails or when the crystal connected to the XA/XB pins fails to oscillate.

Bits 3 to 2: Interface Mode (IF[1:0]). These read-only bits are the latched state of the IF1/MISO and IF0/CSN pins when the RSTN pin transitions high. See section 3.1.

Bits 1 to 0: Auto-Configuration (AC[1:0]). These read-only bits are the latched state of the AC1 and AC0 pins when the RSTN pin transitions high. See section 3.1.

Register Name: GLOBISR
Register Description: Global Functions Status Register
Register Address: 43h

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Name	READY	—	—	—	—	—	—	—
Default	see below	0	0	0	0	0	0	0

Bit 7: Device Ready (READY). This bit indicates the status of the device after reset. It is cleared when the device is reset and set when the device is ready for operation.

Register Name: APLLSR
Register Description: APLL Status Register
Register Address: 48h

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Name	—	—	ALK2L	ALK2	—	—	ALKL	ALK
Default	0	0	0	0	0	0	0	0

Bit 5: APLL Lock 2 Latched Status (ALK2L). This latched status bit is set to 1 when the ALK2 status bit changes state (set or cleared). ALK2L is cleared when written with a 1.

Bit 4: APLL Lock Status 2 (ALK2). This real-time status bit provides one type of APLL lock status. System software should consider the APLL locked when ALK (bit 0) is set to 1 AND ALK2=1.

Bit 1: APLL Lock Latched Status (ALKL). This latched status bit is set to 1 when the ALK status bit changes state (set or cleared). ALKL is cleared when written with a 1.

Bit 0: APLL Lock Status (ALK). This real-time status bit indicates one type of APLL lock status. System software should consider the APLL locked when ALK=1 AND ALK2 (bit 4) is set to 1.

0 = Not locked

1 = Locked

Register Name: PASR
Register Description: Phase Adjust Status Register
Register Address: 4Dh

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Name	—	—	—	—	—	ADJL	BUSY	ARMED
Default	1	0	0	0	0	1	0	0

Bit 2: Phase Adjustment Finished (ADJL). This latched status bit is set when the output phase adjustment is completed for all participating outputs. Writing a 1 to this bit clears it. See section 3.3.2.

- 0 = Output phase adjustment has not completed
- 1 = Output phase adjustment has completed

Bit 1: Phase Adjustment Busy (BUSY). This bit is a real time status that indicates that the output phase adjustment has been triggered and is in progress on the participating outputs. See section 3.3.2.

- 0 = Output phase adjustment is not in progress
- 1 = Output phase adjustment is in progress

Bit 0: Phase Adjustment Armed (ARMED). This bit is a real time status that indicates that the output phase adjustment is armed and waiting for a trigger. It is cleared when the trigger event occurs. See section 3.3.2.

- 0 = Output phase adjustment is not armed
- 1 = Output phase adjustment is armed

Register Name: OCxSR
Register Description: Output Clock x Status Register
Register Address: OC1: 53h, OC2: 54h, OC3: 55h

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Name	—	—	—	—	STARTL	—	STOPL	STOPD
Default	0	0	0	0	0	0	see note	see note

Bit 3: (STARTL). This latched status bit is set when the output clock signal has been started after being stopped. Writing a 1 to this bit clears it. See section 3.3.3.

- 0 = Output clock signal has not resumed from being stopped
- 1 = Output clock signal has resumed from being stopped

Bit 1: (STOPL). This latched status bit is set when the output clock signal has been stopped. Writing a 1 to this bit clears it. See section 3.3.3.

- 0 = Output clock signal has not stopped
- 1 = Output clock signal has stopped

Bit 0: (STOPD). This real-time status bit is high when the output clock signal is stopped and low when the output clock is not stopped. See section 3.3.3.

- 0 = Output clock signal is not stopped
- 1 = Output clock signal is stopped

Note: STOPL and STOPD are controlled by logic that does not have a clock at reset. Therefore their reset values are indeterminate. They will become 0 when the output clock path is configured and one of the high-speed clocks from the APLL is connected to the logic.

4.3.3 Output Clock Configuration Registers

Register Name: OCxCR1
Register Description: Output Clock x Configuration Register 1
Register Address: OC1: 200h, OC2: 210h, OC3: 220h

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Name	PHEN	—	—	—	—	—	—	—
Default	see below	0	0	0	0	1	0	1

Bit 7: Phase Adjust Enable (PHEN). This bit enables this output to participate in phase adjustment/alignment. See section 3.3.2.

- 0 = Phase adjustment/alignment disabled for this output
- 1 = Phase adjustment/alignment enabled for this output

PHEN default value:

	OC1	OC2	OC3
Config0	1	0	0
Config1	1	1	0
Config2	1	1	0
Config3	1	1	1

Register Name: OCxCR2
Register Description: Output Clock x Configuration Register 2
Register Address: OC1: 201h, OC2: 211h, OC3: 221h

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Name	—	POL	DRIVE[1:0]	STOPDIS	—	—	—	—
Default	0	see below	see below	0	varies over config and output #			

Bit 6: Clock Path Polarity (POL). The clock path to the output is inverted when this bit set. The default value for this bit is 1 for OC2 in config2; otherwise the default value is 0. See section 3.3.1.

Bits 5 to 4: CMOS/HSTL Output Drive Strength (DRIVE[1:0]). The CMOS/HSTL output drivers have four equal sections that can be enabled or disabled to achieve four different drive strengths from 1x to 4x. When the output power supply VDDOx is 3.3V or 2.5V, the user should start with 1x and only increase drive strength if the output is highly loaded and signal transition time is unacceptable. When VDDOx is 1.8V or 1.5V the user should start with 4x and only decrease drive strength if the output signal has unacceptable overshoot. See section 3.3.1. This field only applies in Config2 for OC2 (HSTL) and in Config3 for OC3 (CMOS). Otherwise it is ignored. The default value is 01 for OC2 in Config2; otherwise it is 00.

- 00 = 1x
- 01 = 2x
- 10 = 3x
- 11 = 4x

Bit 3: Stop Disable (STOPDIS). This bit causes the output to become disabled (high impedance) while the output clock is stopped. See section 3.3.3.

- 0 = Do not disable the output while stopped
- 1 = Disable the output while stopped

Register Name: OCxPH
Register Description: Output Clock x Phase Adjust Register
Register Address: OC1: 207h, OC2: 217h, OC3: 227h

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Name	PHADJ[7:0]							
Default	See below							

Bits 7 to 0: Phase Adjust Value (PHADJ[7:0]). When `OCxCR1.PHEN=1`, this field specifies the phase adjustment of the output clock during a phase adjustment event. When `OCxCR1.PHEN=0`, this field is ignored. The specified phase adjustment occurs once during a phase adjustment event. The format of the field is 2's-complement with the LSB being one half of an APLL output clock period. See section [3.3.2](#).

- 00000000 = 0.0 UI
- 00000001 = +0.5 UI
- 00000010 = +1.0 UI
- 00000011 = +1.5 UI
- ...
- 01111110 = +63.0 UI
- 01111111 = +63.5 UI
- 10000000 = -64.0 UI
- 10000001 = -63.5 UI
- ...
- 11111101 = -1.5 UI
- 11111110 = -1.0 UI
- 11111111 = -0.5 UI

Default value:

	OC1	OC2	OC3
Config0	0	0	0
Config1	0	0	0
Config2	2	0	0
Config3	2	2	0

Register Name: OCxSTOP
Register Description: Output Clock x Start Stop Register
Register Address: OC1: 208h, OC2: 218h, OC3: 228h

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Name	STOP	—	SRC[3:0]			MODE[1:0]		
Default	0	0	0	0	0	0	0	0

Bit 7: Output Clock Stop (STOP). When SRC=0000, this bit is used to stop the output clock high or low. The output stays stopped while this bit is high. See section 3.3.3.

- 0 = Do not stop the output clock
- 1 = Stop the output clock

Bits 5 to 2: Output Clock Stop Source (SRC[3:0]). This field specifies the source of the stop signal. See section 3.3.3.

- 0000 = STOP bit
- 0001 = The arming of a phase adjustment (signal stopped when PASR.ARMED is asserted; signal started when PASR.ADJL is asserted)
- 0010 to 1111 = {unused values}

Bits 1 to 0: Output Clock Stop Mode (MODE[1:0]). This field selects the mode of the start-stop function. See section 3.3.3.

- 00 = Never stop
- 01 = Stop High: stop after rising edge of output clock, start after falling edge of output clock
- 10 = Stop Low: stop after falling edge of output clock, start after rising edge of output clock
- 11 = {unused value}

The following table shows which pin(s) stop high or low as specified above for each output signal format:

Signal Format	Pin that Stops As Specified
CML	OCxP
HSTL	OCxN
Two CMOS, OCxP in phase with OCxN	OCxP and OCxN
One CMOS, OCxN enabled	OCxN
One CMOS, OCxP enabled	OCxP
Two CMOS, OCxP inverted vs. OCxN	OCxN

Notes:

1. The highest priority condition for an output is when it is stopped and OCxCR2.STOPDIS=1. When this condition occurs both OCxP and OCxN become high-impedance regardless of the state of the control bits mentioned below.
2. When the above situation does not apply, OCxCR2.POL=1 changes Stop High to Stop Low and vice versa.

5. Electrical Characteristics

Absolute Maximum Ratings

Parameter	Symbol	Min.	Max.	Units
Supply voltage, nominal 1.8V	VDD18	-0.3	1.98	V
Supply voltage, nominal 3.3V	VDD33	-0.3	3.63	V
Supply voltage, VDDOx (x=1,2,3)	VDDOx	-0.3	3.63	V
Voltage on XA, any OCxP/N pin	VANAPIN	-0.3	3.63	V
Voltage on any digital I/O pin	VDIGPIN	-0.3	5.5	V
Storage Temperature Range	T _{ST}	-55	+125	°C

* Exceeding these values may cause permanent damage. Functional operation under these conditions is not implied.

* Voltages are with respect to ground (VSS) unless otherwise stated.

Note 1: The typical values listed in the tables of Section 5 are not production tested.

Note 2: Specifications to -40°C and 85°C are guaranteed by design or characterization and not production tested.

Table 5 - Recommended DC Operating Conditions

Parameter	Symbol	Min.	Typ.	Max.	Units
Supply voltage, nominal 1.8V	VDD18	1.71	1.8	1.89	V
Supply voltage, nominal 3.3V	VDD33	3.135	3.3	3.465	V
Supply voltage, VDDOx (x=1,2,3)	VDDOx	1.425	1.5	1.575	V
		1.71	1.8	1.89	
		2.375	2.5	2.625	
		3.135	3.3	3.465	
Operating temperature	T _A	-40		+85	°C

Table 6 - Electrical Characteristics: Supply Currents

Characteristics	Symbol	Min.	Typ. ¹	Max	Units	Notes
Total current, all 1.8V supply pins, Config 0	I _{DD18}		93		mA	
Total current, all 3.3V supply pins, Config 0	I _{DD33}		115		mA	
Total current, all 1.8V supply pins, Config 1	I _{DD18}		131		mA	
Total current, all 3.3V supply pins, Config 1	I _{DD33}		132		mA	
Total current, all 1.8V supply pins, Config 2	I _{DD18}		123		mA	
Total current, all 3.3V supply pins, Config 2	I _{DD33}		131		mA	
Total current, all 1.8V supply pins, Config 3	I _{DD18}		161		mA	
Total current, all 3.3V supply pins, Config 3	I _{DD33}		167		mA	

Note 1: Typical values measured at 1.80V and 3.30V supply voltages and 25°C ambient temperature.

Table 7 - Electrical Characteristics: Non-clock CMOS Pins

Characteristics	Symbol	Min.	Typ.	Max.	Units	Notes
Input high voltage, SCL and SDA	V _{IH}	0.7 x VDD33			V	
Input low voltage, SCL and SDA	V _{IL}			0.3 x VDD33	V	
Input high voltage, all other digital inputs	V _{IH}	2.0			V	
Input low voltage, all other digital inputs	V _{IL}			0.8	V	
Input leakage current, RSTN pin	I _{ILPU}	-85		10	μA	Note 1
Input leakage current, all digital inputs	I _{IL}	-10		10	μA	Note 1
Input capacitance	C _{IN}		3	10	pF	
Input capacitance, SCL/SCLK, SDA/MOSI	C _{IN}		3	11	pF	
Input hysteresis, SCL and SDA in I ² C Bus Mode		0.05*			mV	

Characteristics	Symbol	Min.	Typ.	Max.	Units	Notes
		VDD33				
Output leakage (when high impedance)	I_{LO}	-10		10	μA	Note 1
Output high voltage	V_{OH}	2.4			V	$I_o = -3.0\text{mA}$
Output low voltage	V_{OL}			0.4	V	$I_o = 3.0\text{mA}$

Note 1: $0\text{V} < V_{IN} < \text{VDD33}$ for all other digital inputs.

Note 2: V_{OH} does not apply for SCL and SDA in I²C interface mode since they are open drain.

Table 8 - Electrical Characteristics: XA Clock Input

This table covers the case when there is no external crystal connected and an external oscillator or clock signal is connected to the XA pin.

Characteristics	Symbol	Min.	Typ.	Max.	Units	Notes
Input high voltage, XA	V_{IH}	1.2			V	
Input low voltage, XA	V_{IL}			0.8	V	
Input frequency on XA pin	f_{IN}		25		MHz	
Input leakage current	I_{IL}	-10		10	μA	
Input duty cycle		40		60	%	

Table 9 - Electrical Characteristics: CML Clock Outputs

$V_{DDx} = 3.3\text{V} \pm 5\%$ for CML operation.

Characteristics	Symbol	Min.	Typ.	Max.	Units	Notes
Output frequency	f_{OCML}		100		MHz	
Output high voltage, single-ended, OCxP or OCxN	$V_{OH,S}$		$V_{DDOx} - 0.2$		V	AC coupled to 50 Ω termination
Output low voltage, single-ended, OCxP or OCxN	$V_{OL,S}$		$V_{DDOx} - 0.6$		V	
Output common mode voltage	$V_{CM,S}$		$V_{DDOx} - 0.4$		V	
Output differential voltage	$ V_{OD,S} $	320	400	500	mV	
Output differential voltage, peak-to-peak	$ V_{OD,S,PP} $	640	800	1000	mV _{P-P}	
Difference in Magnitude of Differential Voltage for Complementary States	V_{DOS}			50	mV	
Output Rise/Fall Time	t_R, t_F		150		ps	20%-80%
Output Duty Cycle		45	50	55	%	
Output Impedance	R_{OUT}		50		Ω	Single Ended, to V_{DDOx}
Mismatch in a pair	ΔR_{OUT}			10	%	

Note 1: The differential CML outputs can easily be interfaced to LVDS, LVPECL, CML and other differential inputs on neighboring ICs using a few external passive components. See [Figure 9](#) for details.

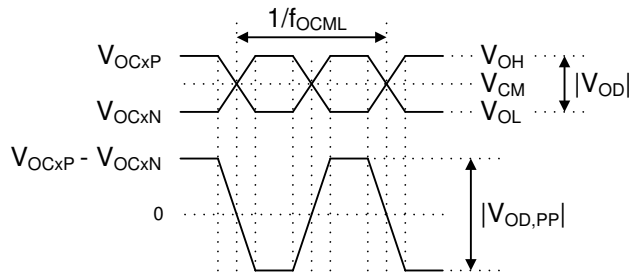


Figure 8 - Electrical Characteristics: CML Clock Outputs

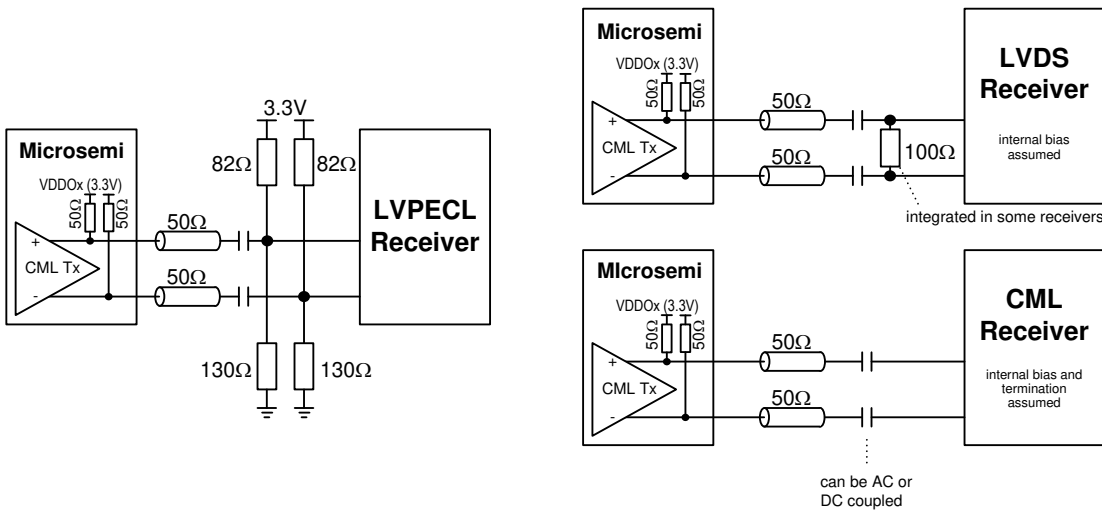


Figure 9 - Example External Components for CML Output Signals

Table 10 - Electrical Characteristics: CMOS and HSTL (Class I) Clock Outputs

Characteristics	Symbol	Min.	Typ.	Max.	Units	Notes
Output frequency	f_{OCMOS}	25			MHz	
Output high voltage	V_{OH}	$V_{DDOx} - 0.4$		V_{DDOx}	V	Notes 2, 3
Output low voltage	V_{OL}	0		0.4	V	Notes 2, 3
Output rise/fall time, $V_{CCOx}=1.8V$, $OCxCR2.DRIVE=4x$	t_R, t_F		0.4		ns	2pF load
Output rise/fall time, $V_{CCOx}=1.8V$, $OCxCR2.DRIVE=4x$			1.2		ns	15pF load
Output rise/fall time, $V_{CCOx}=3.3V$, $OCxCR2.DRIVE=1x$			0.7		ns	2pF load
Output rise/fall time, $V_{CCOx}=3.3V$, $OCxCR2.DRIVE=1x$			2.2		ns	15pF load
Output duty cycle		45	50	55	%	Note 4
Output duty cycle		42	50	58	%	Notes 5, 6
Output duty cycle, $OCxNEG$ single-ended			50		%	Note 5
Output duty cycle, $OCxPOS$ single-ended			46		%	Note 5
Output current when output disabled			10		μA	

Note 1: Measured with a series resistor of 33 Ω and a 5pF load capacitance unless otherwise specified.

Note 2: For HSTL Class I, V_{OH} and V_{OL} apply for both unterminated loads and for symmetrically terminated loads, i.e. 50 Ω to $V_{DDOx}/2$.

Note 3: For $V_{DDOx}=3.3V$ and $OCxCR2.DRIVE=1x$, $I_o=4mA$. For $V_{DDOx}=1.5V$ and $OCxCR2.DRIVE=4x$, $I_o=8mA$.

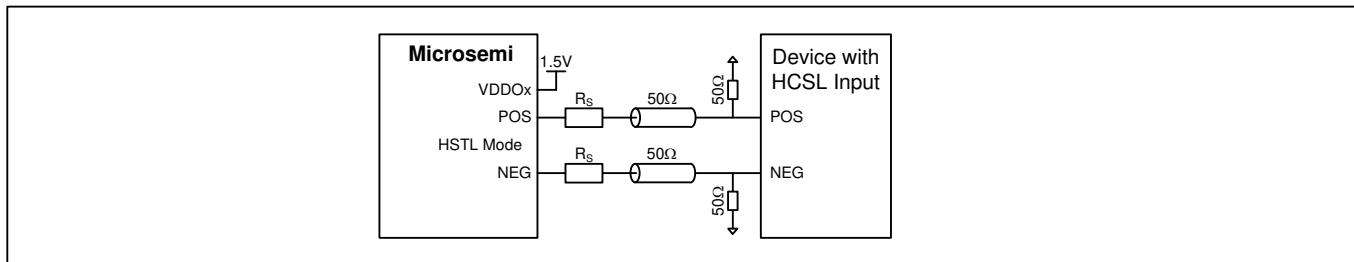
Note 4: $V_{DDOx} \geq 1.8V$.

Note 5: $V_{DDOx} < 1.8V$.

Note 6: Measured differentially.

Interfacing to HCSL Components

In Config2, output OC2 is HSTL mode. HSTL mode with $V_{DDO2}=1.8V$ can provide an HCSL-compatible signal (V_{OH} typ. 0.75V) to a neighboring component when configured as shown in Figure 10 below. The resistor R_S should be 20 Ω .


Figure 10 - Example External Components for HCSL Output Signals
Table 11 - Electrical Characteristics: Typical Input-to-Output Clock Delay

Mode	Delay, Input Clock Edge to Output Clock Edge
All Modes	Non-deterministic but constant as long as the APLL remains locked and output clock phases are not adjusted as described in section 3.3.2.1.

Table 12 - Electrical Characteristics: Typical Output-to-Output Clock Delay

Mode	Delay, Output Clock Edge to Output Clock Edge
All Modes	<100ps Requires phase adjustment and phase alignment capability described in section 3.3.2.

Table 13 - Electrical Characteristics: SPI Slave Interface Timing

Characteristics (Notes 1 to 3)	Symbol	Min.	Typ.	Max.	Units	Notes
SCLK frequency	f_{BUS}			10	MHz	
SCLK cycle time	t_{CYC}	100			ns	
CSN setup to first SCLK edge	t_{SUC}	50			ns	
CSN hold time after last SCLK edge	t_{HDC}	50			ns	
CSN high time	t_{CSH}	50			ns	
SCLK high time	t_{CLKH}	40			ns	
SCLK low time	t_{CLKL}	40			ns	
MOSI data setup time	t_{SUI}	10			ns	
MOSI data hold time	t_{HDI}	10			ns	
MISO enable time from SCLK edge	t_{EN}	0			ns	
MISO disable time from CSN high	t_{DIS}			80	ns	
MISO data valid time	t_{DV}			40	ns	
MISO data hold time from SCLK edge	t_{HDO}	0			ns	
CSN, MOSI input rise time, fall time	t_R, t_F			10	ns	

- Note 1:** All timing is specified with 100pF load on all SPI pins.
- Note 2:** All parameters in this table are guaranteed by design or characterization.
- Note 3:** See timing diagram in [Figure 11](#).

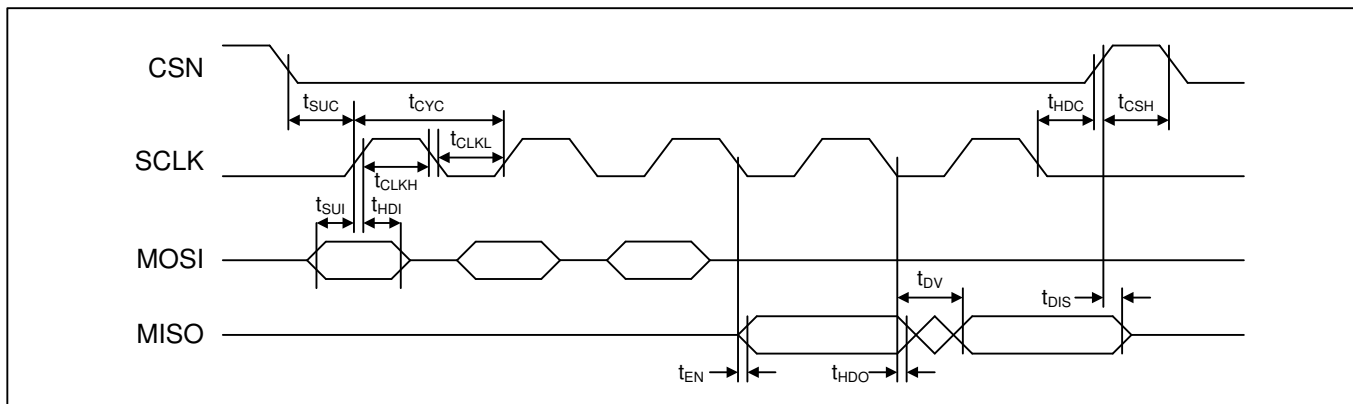


Figure 11 - SPI Slave Interface Timing

Table 14 - Electrical Characteristics: I²C Slave Interface Timing

Characteristics	Symbol	Min.	Typ.	Max.	Units	Notes
SCL clock frequency	f _{SCL}			400	kHz	
Hold time, START condition	t _{HD:STA}	0.6			μs	
Low time, SCL	t _{LOW}	1.3			μs	
High time, SCL	t _{HIGH}	0.6			μs	
Setup time, START condition	t _{SU:STA}	0.6			μs	
Data hold time	t _{HD:DAT}	0		0.9	μs	Notes 2 and 3
Data setup time	t _{SU:DAT}	100			ns	
Rise time	t _R				ns	Note 4
Fall time	t _F	20 + 0.1C _b		300	ns	C _b is cap. of one bus line
Setup time, STOP condition	t _{SU:STO}	0.6			μs	
Bus free time between STOP/START	t _{BUF}	1.3			μs	
Pulse width of spikes which must be suppressed by the input filter	t _{SP}	0		50	ns	

- Note 1:** The timing parameters in this table are specifically for 400kbps Fast Mode. Fast Mode devices are downward-compatible with 100kbps Standard Mode I²C bus timing. All parameters in this table are guaranteed by design or characterization. All values referred to V_{IHmin} and V_{ILmax} levels (see Table 7).
- Note 2:** The device internally provides a hold time of at least 300ns for the SDA signal (referred to the V_{IHmin} of the SCL signal) to bridge the undefined region of the falling edge of SCL. Other devices must provide this hold time as well per the I²C specification.
- Note 3:** The I²C specification indicates that the maximum t_{HD:DAT} spec only has to be met if the device does not stretch the low period (t_{LOW}) of the SCL signal. The device does not stretch the low period of the SCL signal.
- Note 4:** Determined by choice of pull-up resistor.

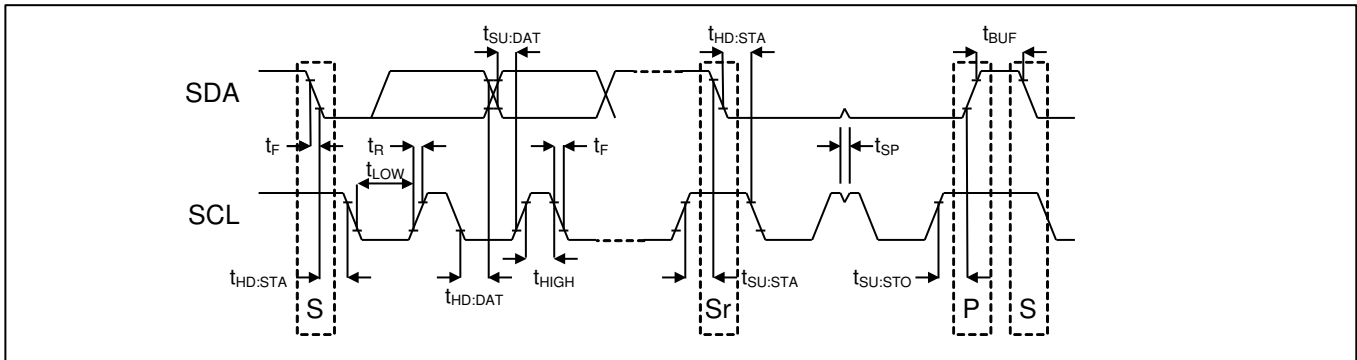


Figure 12 - I²C Slave Interface Timing

6. Package and Thermal Information

6.1 Package Top Mark Format

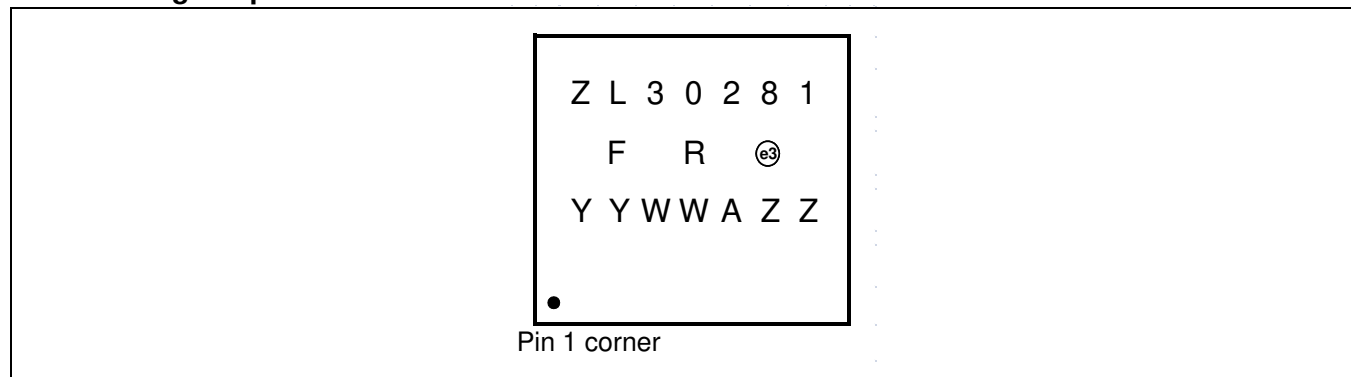


Figure 13 - Device Top Mark

Table 15 – Package Top Mark Legend

Line	Characters	Description
1	ZL30169	Part Number
2	F	Fab Code
2	R	Product Revision Code
2	e3	Denotes Pb-Free Package
3	YY	Last Two Digits of the Year of Encapsulation
3	WW	Work Week of Assembly
3	A	Assembly Location Code
3	ZZ	Assembly Lot Sequence

6.2 Thermal Specifications

Table 16 - 5x5mm QFN Package Thermal Properties

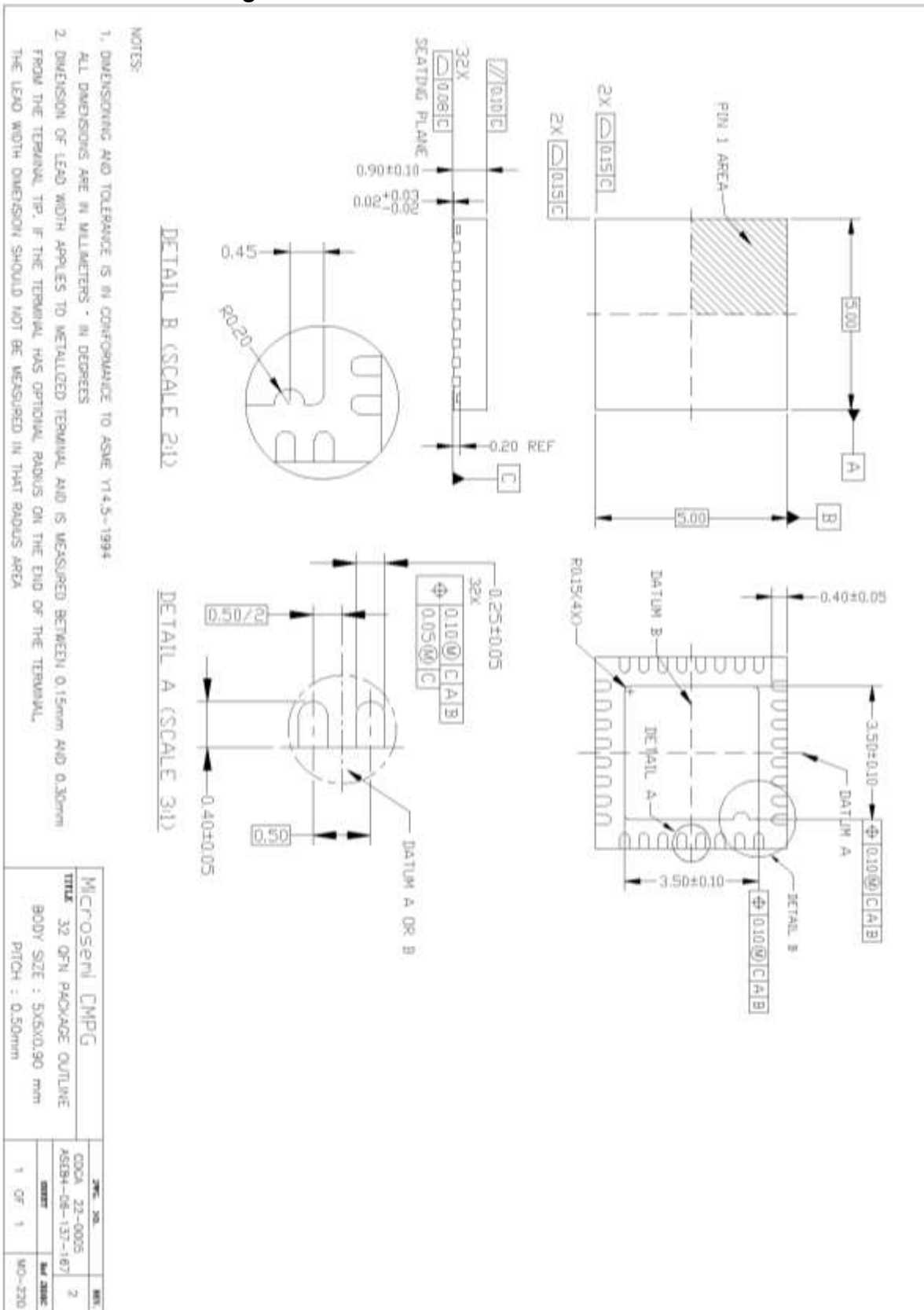
PARAMETER	SYMBOL	CONDITIONS	VALUE	UNITS
Maximum Ambient Temperature	T_A		85	°C
Maximum Junction Temperature	T_{JMAX}		125	°C
Junction to Ambient Thermal Resistance (Note 1)	θ_{JA}	still air	29.6	°C/W
		1m/s airflow	23.3	
		2.5m/s airflow	20.6	
Junction to Board Thermal Resistance	θ_{JB}		9.8	°C/W
Junction to Case Thermal Resistance	θ_{JC}		17.5	°C/W
Junction to Pad Thermal Resistance (Note 2)	θ_{JP}	Still air	3.4	°C/W
Junction to Top-Center Thermal Characterization Parameter	ψ_{JT}	Still air	0.2	°C/W

Note 1: Theta-JA (θ_{JA}) is the thermal resistance from junction to ambient when the package is mounted on an 4-layer JEDEC standard test board and dissipating maximum power.

Note 2: Theta-JP (θ_{JP}) is the thermal resistance from junction to the center exposed pad on the bottom of the package.

Note 3: For all numbers in the table, the exposed pad is connected to the ground plane with a 5x5 array of thermal vias; via diameter 0.33mm; via pitch 0.76mm.

7. Mechanical Drawing



8. Acronyms and Abbreviations

APLL	analog phase locked loop
CML	current mode logic
GbE	gigabit Ethernet
HCSL	high-speed current steering logic
HSTL	high-speed transceiver logic
I/O	input/output
LVDS	low-voltage differential signal
LVPECL	low-voltage positive emitter-coupled logic
PFD	phase/frequency detector
PLL	phase locked loop
pk-pk	peak-to-peak
RMS	root-mean-square
RO	read-only
R/W	read/write
UI	unit interval
UI _{PP} or UI _{P-P}	unit interval, peak to peak
XO	crystal oscillator

9. Data Sheet Revision History

Revision	Description
02-Aug-2017	First full draft
07-Aug-2017	Edited section 3.3 to remove concepts that don't apply to ZL30281.
08-Aug-2017	Deleted Figure 8 which does not apply to ZL30281. Deleted note 1 from Table 10 and renumbered remaining notes.
09-Aug-2017	Below Table 10, simplified Interfacing to HCSL components to apply only to OC2 in Config2 with VDDO2=1.8V. Made similar edits to section 3.3.1. In OCxCR2 add text to say when this DRIVE field applies and how default value varies over config # and output #.
21-Sep-2017	Added IDD numbers in Table 6. Removed Preliminary from page headers.
10-May-2018	In section 6 added package top mark format.
13-Jun-2018	On page 1 changed wording to indicate PCIe 1-4 compliance.



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